

Title (en)
ELECTRICALLY CONDUCTING CONNECTION WITH INSULATING CONNECTION MEDIUM

Title (de)
ELEKTRISCH LEITENDE VERBINDUNG MIT ISOLIERENDEM VERBINDUNGSMEDIUM

Title (fr)
LIAISON ÉLECTROCONDUCTRICE AVEC AGENT DE LIAISON ISOLANT

Publication
EP 2018664 A1 20090128 (DE)

Application
EP 07722445 A 20070516

Priority
• DE 2007000897 W 20070516
• DE 102006023683 A 20060519
• DE 102006028692 A 20060622

Abstract (en)
[origin: WO2007134581A1] Device with a first component (5) with a first surface (6), a second component (8) with a second surface (9), and a connecting layer (7) between the first surface (6) of the first component (5) and the second surface (9) of the second component (8), in which the connecting layer (7) comprises an electrically insulating adhesive, and an electrically conducting contact exists between the first surface (6) of the first component (5) and the second surface (9) of the second component (8).

IPC 8 full level
H01L 21/58 (2006.01); **H01L 33/00** (2010.01); **H01L 33/20** (2010.01)

CPC (source: EP KR US)
H01L 24/27 (2013.01 - EP US); **H01L 24/32** (2013.01 - EP US); **H01L 24/83** (2013.01 - EP US); **H01L 33/02** (2013.01 - KR); **H05K 3/321** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 33/0093** (2020.05 - EP US); **H01L 33/20** (2013.01 - EP US); **H01L 2224/26145** (2013.01 - EP US); **H01L 2224/27013** (2013.01 - EP US); **H01L 2224/32057** (2013.01 - EP US); **H01L 2224/32245** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48247** (2013.01 - EP US); **H01L 2224/73265** (2013.01 - EP US); **H01L 2224/83051** (2013.01 - EP US); **H01L 2224/83385** (2013.01 - EP US); **H01L 2224/838** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/01011** (2013.01 - EP US); **H01L 2924/01013** (2013.01 - EP US); **H01L 2924/01015** (2013.01 - EP US); **H01L 2924/01019** (2013.01 - EP US); **H01L 2924/0103** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/01047** (2013.01 - EP US); **H01L 2924/01049** (2013.01 - EP US); **H01L 2924/0105** (2013.01 - EP US); **H01L 2924/01068** (2013.01 - EP US); **H01L 2924/01074** (2013.01 - EP US); **H01L 2924/01075** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **H01L 2924/0132** (2013.01 - EP US); **H01L 2924/014** (2013.01 - EP US); **H01L 2924/07802** (2013.01 - EP US); **H01L 2924/10155** (2013.01 - EP US); **H01L 2924/10158** (2013.01 - EP US); **H01L 2924/12036** (2013.01 - EP US); **H01L 2924/12041** (2013.01 - EP US); **H01L 2924/12044** (2013.01 - EP US); **H01L 2924/15788** (2013.01 - EP US); **H01L 2924/19043** (2013.01 - EP US); **H05K 2201/0373** (2013.01 - EP US)

Citation (search report)
See references of WO 2007134581A1

Designated contracting state (EPC)
DE

Designated extension state (EPC)
AL BA HR MK RS

DOCDB simple family (publication)
DE 102006028692 A1 20071122; **DE 102006028692 B4 20210902**; EP 2018664 A1 20090128; JP 2009537970 A 20091029; JP 5208922 B2 20130612; KR 101367545 B1 20140226; KR 20090027639 A 20090317; TW 200807646 A 20080201; TW I357639 B 20120201; US 2009302429 A1 20091210; US 8102060 B2 20120124; WO 2007134581 A1 20071129

DOCDB simple family (application)
DE 102006028692 A 20060622; DE 2007000897 W 20070516; EP 07722445 A 20070516; JP 2009510280 A 20070516; KR 20087030710 A 20070516; TW 96117569 A 20070517; US 30156607 A 20070516